

# SMD Type 940nm Infrared Emitter

#### **Features**

- Small double-end package
- Viewing Angle at X axis (Note3) =  $\pm 80^{\circ}$
- High reliability
- Good spectral matching to Si photo detector
- RoHS compliance

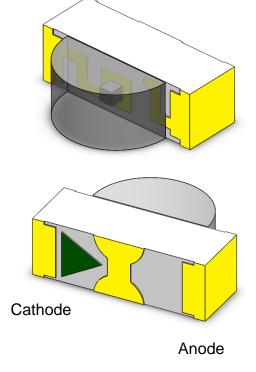
## **Applications**

- Infrared sensor
- Light barrier
- Infrared Touch Panel Solutions

#### **Description**

The IRP3010M20-B60 is a GaAlAs infrared LED housed in a miniature SMD package. The device has a peak wavelength of 940nm LED spectrally matched with phototransistor or photodiode.

### **Package Outline**



#### **Schematic**



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# Absolute Maximum Rating at 25°C

Symbol	Parameters	Ratings	Units	Notes
l <sub>F</sub>	Continuous Forward Current	70	mA	
I <sub>FP</sub>	Peak Forward Current	1.0	Α	1
V <sub>R</sub>	Reverse Voltage	5	V	
T <sub>opr</sub>	Operating Temperature	-40 ~ +85	°C	
T <sub>stg</sub>	Storage Temperature	-40 ~ +100	°C	
T <sub>sol</sub>	Soldering Temperature	260	°C	2
P <sub>D</sub>	Power Dissipation at(or below) 25°CFree Air Temperature	119	mW	

## Electro-Optical Characteristics TA = 25°C (unless otherwise specified)

#### **Optical Characteristics**

Symbol	Parameters	Test Conditions	Min	Тур	Max	Units	Notes
lo	Padient Intensity	I <sub>F</sub> =20mA	0.5	0.85	-	m\\//or	W/sr
le	Radiant Intensity	I <sub>F</sub> =70mA	-	3.0	-	mvv/sr	
λр	Peak Wavelength	I <sub>F</sub> =20mA	-	940	-	nm	
Δλ	Spectral Bandwidth	I <sub>F</sub> =20mA	-	50	-	nm	
01/2	Angle of Half Intensity (X)	1 20m A	-	±80	-	doa	3
θ1/2	Angle of Half Intensity (Y)	I <sub>F</sub> =20mA	-	±75	-	deg	

#### **Electrical Characteristics**

Symbol	Parameters	Test Conditions	Min	Тур	Max	Units	Notes
\/-	Forward Voltage	I <sub>F</sub> =20mA	1.0	1.2	1.5	W	
V <sub>F</sub> Forward Voltage	I <sub>F</sub> =70mA	1.1	1.34	1.7			
I <sub>R</sub>	Reverse Current	V <sub>R</sub> =5V	-	-	10	μA	

#### Notes:

- 1 : I<sub>FP</sub> Conditions--Pulse Width≦ 100µs and Duty≦ 1%.
- 2 : Soldering time  $\leq\!\!5$  seconds.
- 3: Test condition:

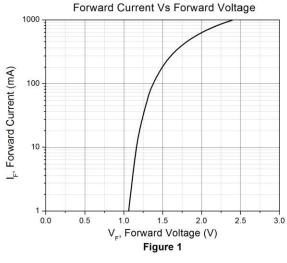


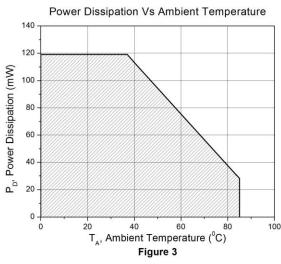


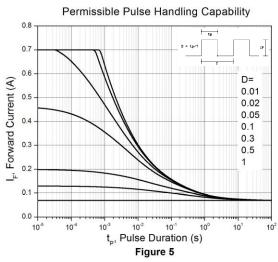


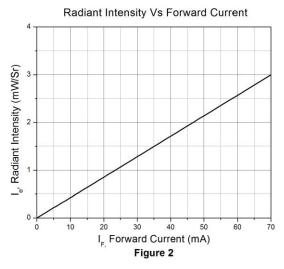
# SMD Type 940nm Infrared Emitter

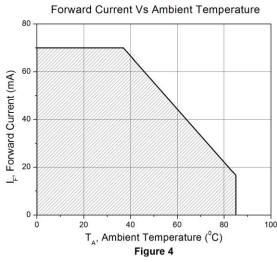
### **Typical Characteristic Curves**

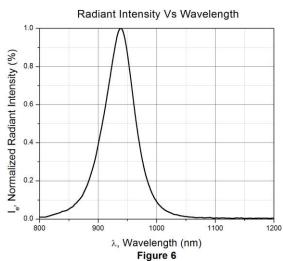












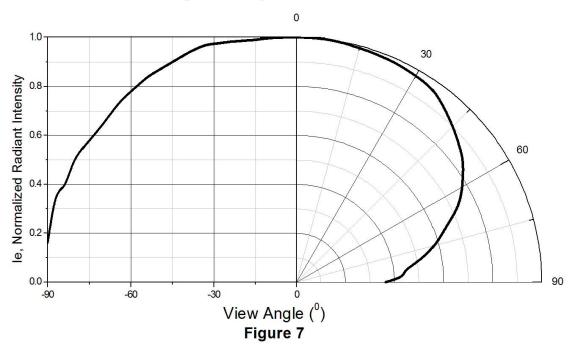




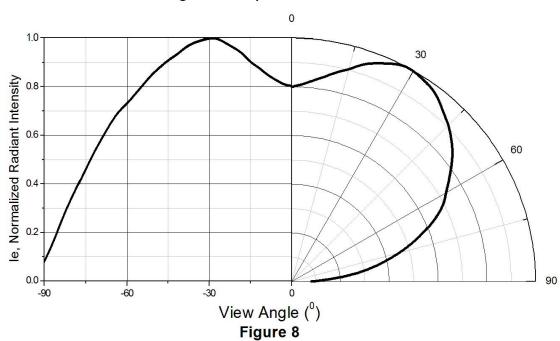
# SMD Type 940nm Infrared Emitter

## **Typical Characteristic Curves**

# Angular Displacement at X axis



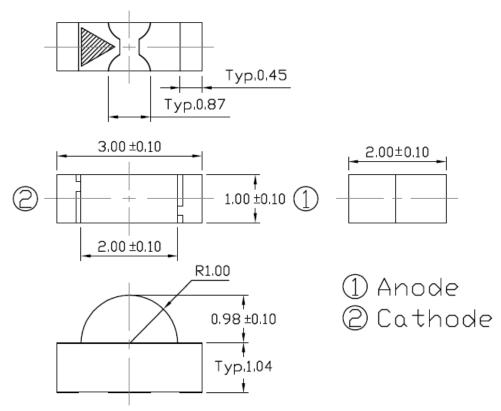
# Angular Displacement at Y axis



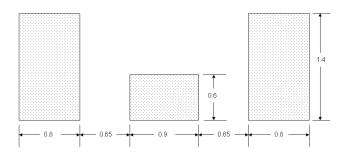


# SMD Type 940nm Infrared Emitter

#### Package Dimension All dimensions are in mm, unless otherwise stated



## Recommended Soldering Mask All dimensions are in mm, unless otherwise stated



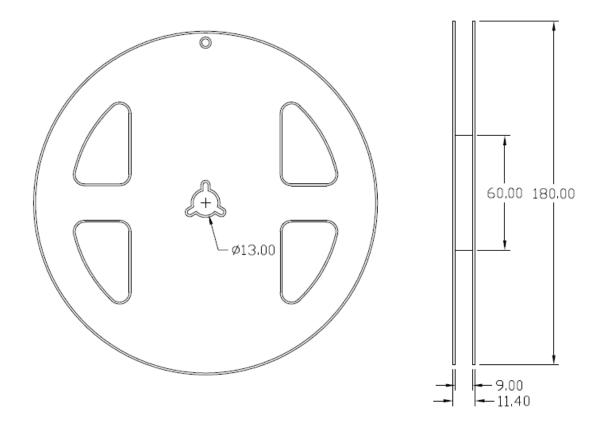
# **Ordering Information**

Part Number	Description	Quantity
IRP3010M20-B60	Tape & Reel	3000 pcs

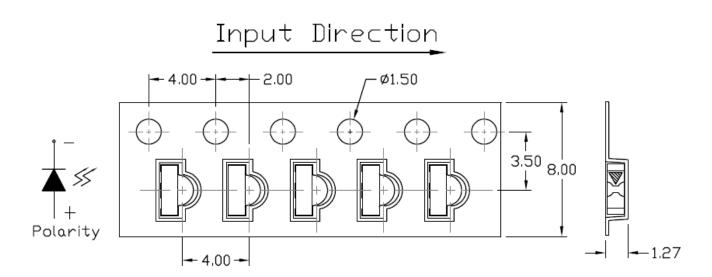


# SMD Type 940nm Infrared Emitter

## Reel Dimension All dimensions are in mm, unless otherwise stated



Tape Dimension All dimensions are in mm, unless otherwise stated

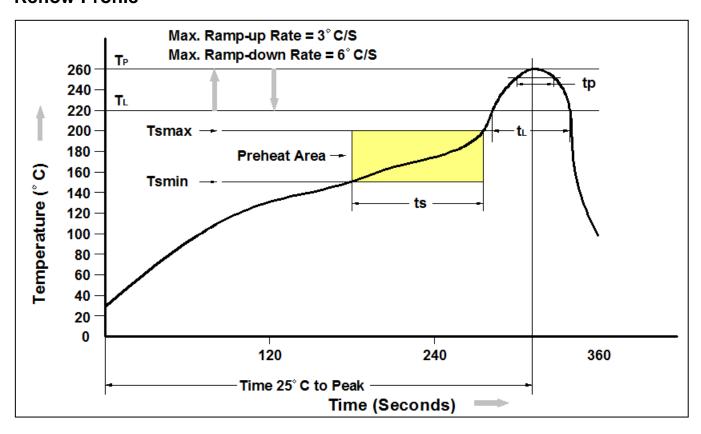






# SMD Type 940nm Infrared Emitter

#### **Reflow Profile**



Profile Feature	Pb-Free Assembly Profile
Temperature Min. (Tsmin)	150°C
Temperature Max. (Tsmax)	200°C
Time (ts) from (Tsmin to Tsmax)	60-120 seconds
Ramp-up Rate (t∟ to t⊳)	3°C/second max.
Liquidous Temperature (T <sub>L</sub> )	217°C
Time (t <sub>L</sub> ) Maintained Above (T <sub>L</sub> )	60 – 150 seconds
Peak Body Package Temperature	260°C +0°C / -5°C
Time (t <sub>P</sub> ) within 5°C of 260°C	30 seconds
Ramp-down Rate (T <sub>P</sub> to T <sub>L</sub> )	6°C/second max
Time 25°C to Peak Temperature	8 minutes max.



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